

## SN74LVC3G34 Triple Buffer Gate

### 1 Features

- Available in the Texas Instruments NanoFree™ Package
- Supports 5.5-V  $V_{CC}$  Operation
- Inputs Accept Voltages to 5.5 V
- Max  $t_{pd}$  of 4.1 ns at 3.3 V
- Low Power Consumption, 10- $\mu$ A Maximum  $I_{CC}$
- $\pm$ 24-mA Output Drive at 3.3 V
- Typical  $V_{OLP}$  (Output Ground Bounce) <0.8 V at  $V_{CC} = 3.3$  V,  $T_A = 25^\circ\text{C}$
- Typical  $V_{OHV}$  (Output  $V_{OH}$  Undershoot) >2 V at  $V_{CC} = 3.3$  V,  $T_A = 25^\circ\text{C}$
- $I_{off}$  Supports Live Insertion, Partial-Power-Down Mode, and Back-Drive Protection
- Can Be Used as a Down Translator to Translate Inputs From a Maximum of 5.5 V Down to the  $V_{CC}$  Level
- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II
- ESD Protection Exceeds JESD 22
  - 2000-V Human Body Model (A114-A)
  - 200-V Machine Model (A115-A)
  - 1000-V Charged-Device Model (C101)

### 2 Applications

- AV Receivers
- Audio Docks: Portable
- Blu-ray Players and Home Theaters
- DVD Recorders and Players
- Embedded PCs
- MP3 Players and Recorders (Portable Audio)
- Personal Digital Assistant (PDA)
- Power: Telecom/Server AC/DC Supply: Single Controller: Analog and Digital
- Solid-State Drive (SSD): Client and Enterprise
- TV: LCD/Digital and High-Definition (HDTV)
- Tablets: Enterprise
- Video Analytics: Servers
- Wireless Headsets, Keyboards, and Mice

### 3 Description

The SN74LVC3G34 device is a triple buffer gate designed for 1.65-V to 5.5-V  $V_{CC}$  operation. The SN74LVC3G34 device performs the Boolean function  $Y = A$  in positive logic.

NanoFree package technology is a major breakthrough in IC packaging concepts, using the die as the package.

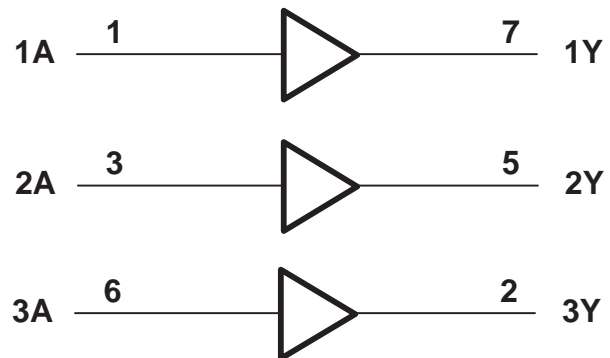
This device is fully specified for partial-power-down applications using  $I_{off}$ . The  $I_{off}$  circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.

#### Device Information<sup>(1)</sup>

PART NUMBER	PACKAGE	BODY SIZE (NOM)
SN74LVC3G34DCT	SM8 (8)	2.95 mm x 2.80 mm
SN74LVC3G34DCU	VSSOP (8)	2.30 mm x 2.00 mm
SN74LVC3G34YZP	DSBGA (8)	1.91 mm x 0.91 mm

(1) For all available packages, see the orderable addendum at the end of the data sheet.

#### Simplified Schematic



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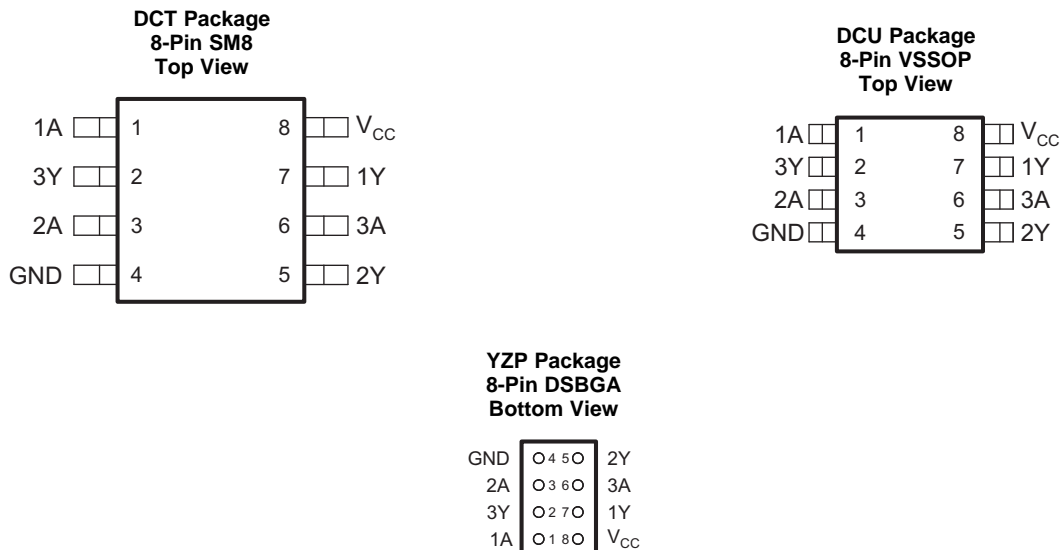
## 4 Revision History

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

<b>Changes from Revision J (February 2007) to Revision K</b>	<b>Page</b>
• Updated document to new TI data sheet format .....	<b>1</b>
• Removed <i>Ordering Information</i> table .....	<b>1</b>
• Updated <i>Features</i> section .....	<b>1</b>
• Updated operating temperature range .....	<b>4</b>

<b>Changes from Revision K (November 2013) to Revision L</b>	<b>Page</b>
• Added <i>Applications</i> , <i>Device Information</i> table, <i>Pin Configuration and Functions</i> section, <i>ESD Ratings</i> table, <i>Thermal Information</i> table, <i>Typical Characteristics</i> section, <i>Feature Description</i> section, <i>Device Functional Modes</i> , <i>Application and Implementation</i> section, <i>Power Supply Recommendations</i> section, <i>Layout</i> section, <i>Device and Documentation Support</i> section, and <i>Mechanical, Packaging, and Orderable Information</i> section .....	<b>1</b>
• Deleted part number from <i>Switching Characteristics</i> table headers .....	<b>5</b>

## 5 Pin Configuration and Functions



### Pin Functions<sup>(1)</sup>

PIN		I/O	DESCRIPTION
NAME	NO.		
1A	1	I	Buffer Input 1
1Y	7	O	Buffer Output 1
2A	3	I	Buffer Input 2
2Y	5	O	Buffer Output 2
3A	6	I	Buffer Input 3
3Y	2	O	Buffer Output 3
GND	4	—	Ground pin
V <sub>CC</sub>	8	—	Power pin

(1) See mechanical drawings for dimensions

## 6 Specifications

### 6.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)<sup>(1)</sup>

	MIN	MAX	UNIT
V <sub>CC</sub> Supply voltage	-0.5	6.5	V
V <sub>I</sub> Input voltage <sup>(2)</sup>	-0.5	6.5	V
V <sub>O</sub> Voltage applied to any output in the high-impedance or power-off state <sup>(2)</sup>	-0.5	6.5	V
V <sub>O</sub> Voltage applied to any output in the high or low state <sup>(2)(3)</sup>	-0.5	V <sub>CC</sub> + 0.5	V
I <sub>IK</sub> Input clamp current	V <sub>I</sub> < 0	-50	mA
I <sub>OK</sub> Output clamp current	V <sub>O</sub> < 0	-50	mA
I <sub>O</sub> Continuous output current		±50	mA
Continuous current through V <sub>CC</sub> or GND		±100	mA
T <sub>J</sub> Junction temperature		150	°C
T <sub>stg</sub> Storage temperature	-65	150	°C

- (1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions* is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) The input negative-voltage and output voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
- (3) The value of V<sub>CC</sub> is provided in the *Recommended Operating Conditions* table.

## 6.2 ESD Ratings

		VALUE	UNIT
$V_{(ESD)}$	Electrostatic discharge	Human body model (HBM), per ANSI/ESDA/JEDEC JS-001, all pins <sup>(1)</sup>	2500
		Charged-device model (CDM), per JEDEC specification JESD22-C101, all pins <sup>(2)</sup>	1500

(1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.

(2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

## 6.3 Recommended Operating Conditions<sup>(1)</sup>

		MIN	MAX	UNIT
$V_{CC}$	Supply voltage	Operating	1.65	5.5
		Data retention only	1.5	
$V_{IH}$	High-level input voltage	$V_{CC} = 1.65\text{ V to }1.95\text{ V}$	$0.65 \times V_{CC}$	
		$V_{CC} = 2.3\text{ V to }2.7\text{ V}$	1.7	
		$V_{CC} = 3\text{ V to }3.6\text{ V}$	2	
		$V_{CC} = 4.5\text{ V to }5.5\text{ V}$	$0.7 \times V_{CC}$	
$V_{IL}$	Low-level input voltage	$V_{CC} = 1.65\text{ V to }1.95\text{ V}$	$0.35 \times V_{CC}$	
		$V_{CC} = 2.3\text{ V to }2.7\text{ V}$	0.7	
		$V_{CC} = 3\text{ V to }3.6\text{ V}$	0.8	
		$V_{CC} = 4.5\text{ V to }5.5\text{ V}$	$0.3 \times V_{CC}$	
$V_I$	Input voltage	0	5.5	V
$V_O$	Output voltage	0	$V_{CC}$	V
$I_{OH}$	High-level output current	$V_{CC} = 1.65\text{ V}$	-4	
		$V_{CC} = 2.3\text{ V}$	-8	
		$V_{CC} = 3\text{ V}$	-16	
		$V_{CC} = 4.5\text{ V}$	-24	
$I_{OL}$	Low-level output current	$V_{CC} = 1.65\text{ V}$	4	
		$V_{CC} = 2.3\text{ V}$	8	
		$V_{CC} = 3\text{ V}$	16	
		$V_{CC} = 4.5\text{ V}$	24	
$\Delta t/\Delta v$	Input transition rise or fall rate	$V_{CC} = 1.8\text{ V} \pm 0.15\text{ V}, 2.5\text{ V} \pm 0.2\text{ V}$	20	
		$V_{CC} = 3.3\text{ V} \pm 0.3\text{ V}$	10	ns/V
		$V_{CC} = 5\text{ V} \pm 0.5\text{ V}$	5	
$T_A$	Operating free-air temperature	DCT, DCU Package	-40	125
		YZP Package	-40	85

(1) All unused inputs of the device must be held at  $V_{CC}$  or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, [SCBA004](#).

## 6.4 Thermal Information

THERMAL METRIC <sup>(1)</sup>	SN74LVC3G34			UNIT	
	DCT (SM8)	DCU (VSSOP)	YZP (DSBGA)		
	8 PINS	8 PINS	8 PINS		
$R_{\theta JA}$	Junction-to-ambient thermal resistance	220	227	140	°C/W

(1) For more information about traditional and new thermal metrics, see the *Semiconductor and IC Package Thermal Metrics* application report, [SPRA953](#).

## 6.5 Electrical Characteristics

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V <sub>CC</sub>	MIN	TYP <sup>(1)</sup>	MAX	UNIT	
V <sub>OH</sub>	I <sub>OH</sub> = -100 μA	1.65 V to 5.5 V	V <sub>CC</sub> - 0.1			V	
	I <sub>OH</sub> = -4 mA	1.65 V	1.2				
	I <sub>OH</sub> = -8 mA	2.3 V	1.9				
	I <sub>OH</sub> = -16 mA	3 V	2.4				
	I <sub>OH</sub> = -24 mA		2.3				
	I <sub>OH</sub> = -32 mA		3.8				
V <sub>OL</sub>	I <sub>OL</sub> = 100 μA	1.65 V to 5.5 V			0.1	V	
	I <sub>OL</sub> = 4 mA	1.65 V			0.45		
	I <sub>OL</sub> = 8 mA	2.3 V			0.3		
	I <sub>OL</sub> = 16 mA	3 V			0.4		
	I <sub>OL</sub> = 24 mA	T <sub>A</sub> = -40°C to 85°C	3 V				0.55
							0.75
	I <sub>OL</sub> = 32 mA	T <sub>A</sub> = -40°C to 85°C	4.5 V				0.55
							0.75
I <sub>I</sub>	A inputs	V <sub>I</sub> = 5.5 V or GND	0 to 5.5 V		±5	μA	
I <sub>off</sub>		V <sub>I</sub> or V <sub>O</sub> = 5.5 V	0		±10	μA	
I <sub>CC</sub>		V <sub>I</sub> = 5.5 V or GND, I <sub>O</sub> = 0	1.65 V to 5.5 V		10	μA	
ΔI <sub>CC</sub>		One input at V <sub>CC</sub> - 0.6 V, Other inputs at V <sub>CC</sub> or GND	3 V to 5.5 V		500	μA	
C <sub>I</sub>		V <sub>I</sub> = V <sub>CC</sub> or GND	T <sub>A</sub> = -40°C to 85°C	3.3 V		3.5	pF

(1) All typical values are at V<sub>CC</sub> = 3.3 V, T<sub>A</sub> = 25°C.

## 6.6 Switching Characteristics

over recommended operating free-air temperature range (unless otherwise noted) (see Figure 2)

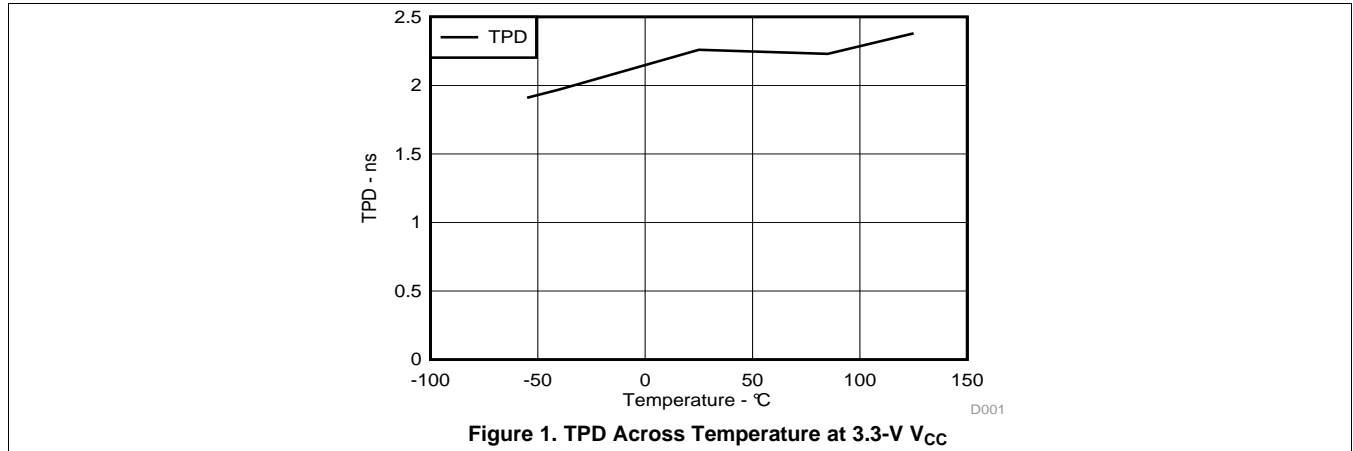
PARAMETER	FROM (INPUT)	TO (OUTPUT)	OPERATING FREE-AIR TEMPERATURE (T <sub>A</sub> )	V <sub>CC</sub>	MIN	MAX	UNIT
t <sub>pd</sub>	A	Y	-40°C to 85°C	V <sub>CC</sub> = 1.8 V ± 0.15 V	3.2	7.9	ns
				V <sub>CC</sub> = 2.5 V ± 0.2 V	1.5	4.4	
				V <sub>CC</sub> = 3.3 V ± 0.3 V	1.4	4.1	
				V <sub>CC</sub> = 5 V ± 0.5 V	1.1	3.2	
t <sub>pd</sub>	A	Y	-40°C to 125°C	V <sub>CC</sub> = 1.8 V ± 0.15 V	3.2	8.9	ns
				V <sub>CC</sub> = 2.5 V ± 0.2 V	1.5	5.4	
				V <sub>CC</sub> = 3.3 V ± 0.3 V	1.4	5.1	
				V <sub>CC</sub> = 5 V ± 0.5 V	1.1	3.8	

## 6.7 Operating Characteristics

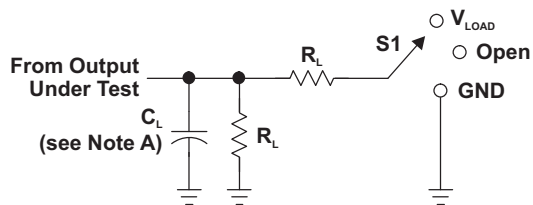
T<sub>A</sub> = 25°C

PARAMETER	TEST CONDITIONS	V <sub>CC</sub>	TYP	UNIT
C <sub>pd</sub> Power dissipation capacitance	f = 10 MHz	V <sub>CC</sub> = 1.8 V	19	pF
		V <sub>CC</sub> = 2.5 V	19	
		V <sub>CC</sub> = 3.3 V	19	
		V <sub>CC</sub> = 5 V	21	

## 6.8 Typical Characteristics



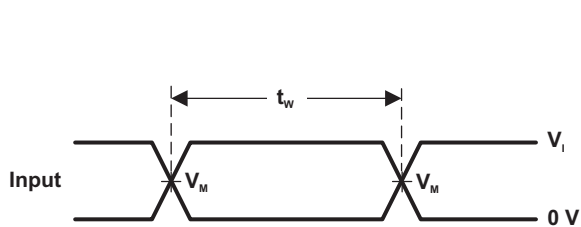
## 7 Parameter Measurement Information



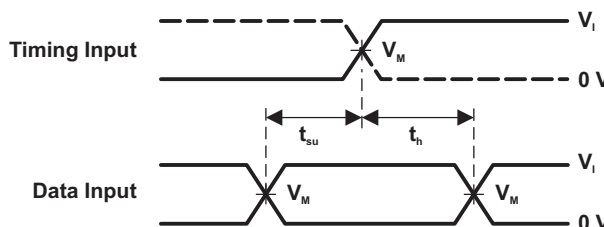
LOAD CIRCUIT

TEST	S1
$t_{PLH}/t_{PHL}$	Open
$t_{PLZ}/t_{PZL}$	$V_{LOAD}$
$t_{PHZ}/t_{PZH}$	GND

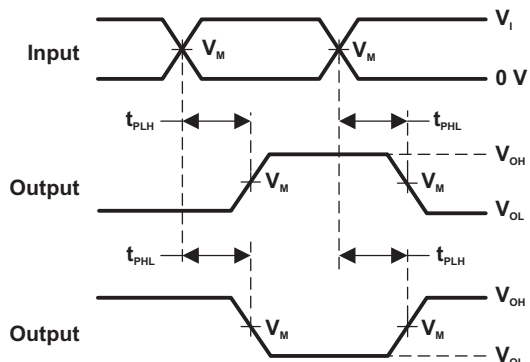
$V_{CC}$	INPUTS		$V_M$	$V_{LOAD}$	$C_L$	$R_L$	$V_{\Delta}$
	$V_i$	$t_i/t_r$					
$1.8\text{ V} \pm 0.15\text{ V}$	$V_{CC}$	$\leq 2\text{ ns}$	$V_{CC}/2$	$2 \times V_{CC}$	30 pF	1 k $\Omega$	0.15 V
$2.5\text{ V} \pm 0.2\text{ V}$	$V_{CC}$	$\leq 2\text{ ns}$	$V_{CC}/2$	$2 \times V_{CC}$	30 pF	500 $\Omega$	0.15 V
$3.3\text{ V} \pm 0.3\text{ V}$	3 V	$\leq 2.5\text{ ns}$	1.5 V	6 V	50 pF	500 $\Omega$	0.3 V
$5\text{ V} \pm 0.5\text{ V}$	$V_{CC}$	$\leq 2.5\text{ ns}$	$V_{CC}/2$	$2 \times V_{CC}$	50 pF	500 $\Omega$	0.3 V



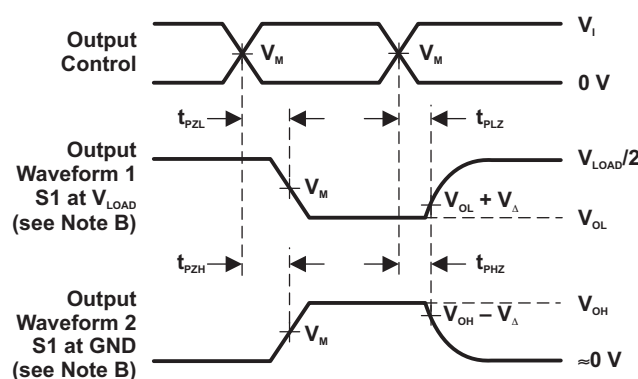
VOLTAGE WAVEFORMS PULSE DURATION



VOLTAGE WAVEFORMS SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS PROPAGATION DELAY TIMES INVERTING AND NONINVERTING OUTPUTS



VOLTAGE WAVEFORMS ENABLE AND DISABLE TIMES LOW- AND HIGH-LEVEL ENABLING

- NOTES: A.  $C_L$  includes probe and jig capacitance.  
 B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.  
 C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz,  $Z_o = 50\ \Omega$ .  
 D. The outputs are measured one at a time, with one transition per measurement.  
 E.  $t_{PLZ}$  and  $t_{PHZ}$  are the same as  $t_{dis}$ .  
 F.  $t_{PZL}$  and  $t_{PZH}$  are the same as  $t_{en}$ .  
 G.  $t_{PLH}$  and  $t_{PHL}$  are the same as  $t_{pd}$ .  
 H. All parameters and waveforms are not applicable to all devices.

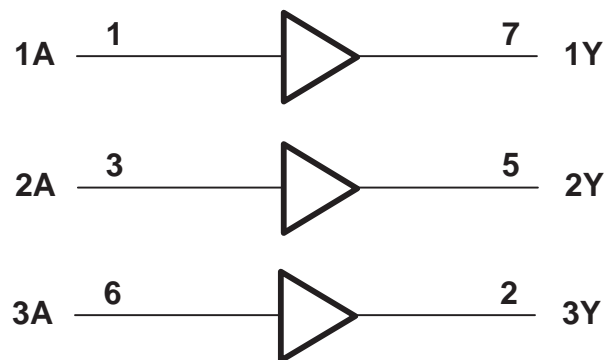
Figure 2. Load Circuit and Voltage Waveforms

## 8 Detailed Description

### 8.1 Overview

The SN74LVC3G34 device contains three buffer gates that each perform the Boolean function  $Y = A$ . This device is fully specified for partial-power-down applications using  $I_{off}$ . The  $I_{off}$  circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.

### 8.2 Functional Block Diagram



### 8.3 Feature Description

The SN74LVC3G34 device has a wider operating voltage range, operating from 1.65 V to 5.5 V, and allows down voltage translation. The SN74LVC3G34  $I_{off}$  feature allows voltages on the inputs and outputs when  $V_{CC}$  is 0 V.

### 8.4 Device Functional Modes

[Table 1](#) lists the functional modes of the SN74LVC3G34.

**Table 1. Function Table**

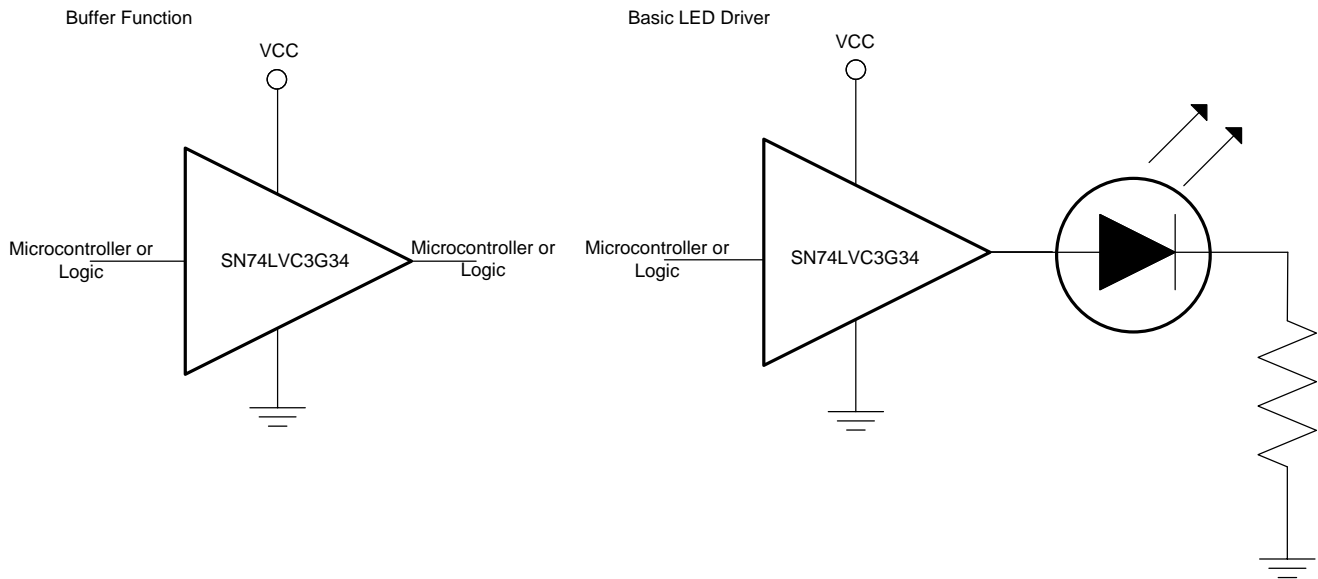
INPUT A	OUTPUT Y
H	H
L	L

## 9 Application and Implementation

### 9.1 Application Information

The SN74LVC3G34 is a high-drive CMOS device that can be used as a buffer with a high output drive, such as an LED application. It can produce 24 mA of drive current at 3.3 V, making it ideal for driving multiple outputs and good for high-speed applications up to 100 MHz. The inputs are 5.5-V tolerant, allowing it to translate down to  $V_{CC}$ .

### 9.2 Typical Application



#### 9.2.1 Design Requirements

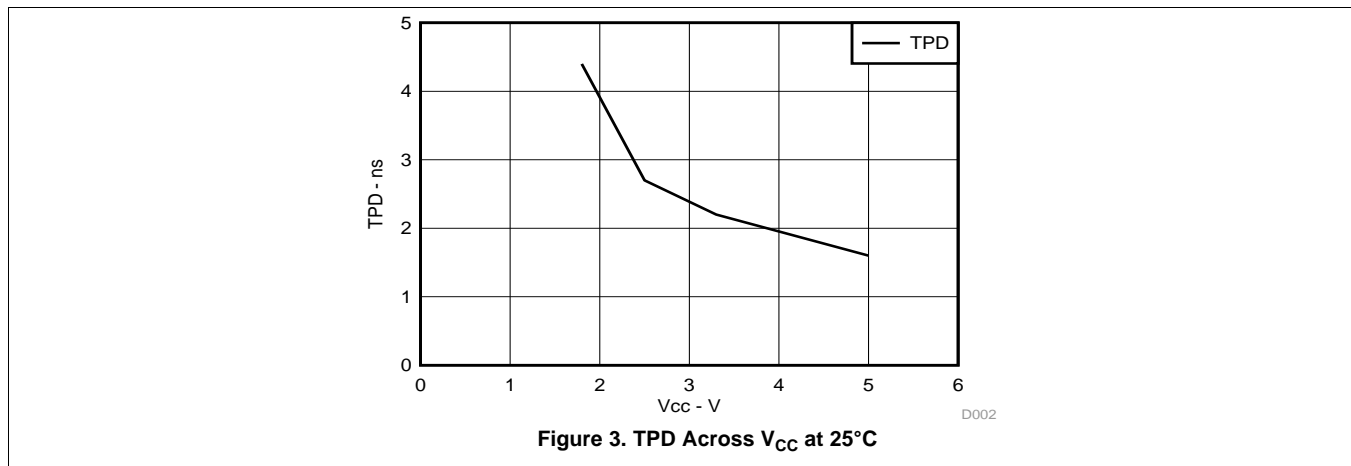
This device uses CMOS technology and has balanced output drive. Take care to avoid bus contention because it can drive currents that would exceed maximum limits. The high drive will also create fast edges into light loads so routing and load conditions must be considered to prevent ringing.

#### 9.2.2 Detailed Design Procedure

1. Recommended Input Conditions
  - Rise time and fall time specs. See ( $\Delta t/\Delta V$ ) in the [Recommended Operating Conditions](#) table.
  - Specified high and low levels. See ( $V_{IH}$  and  $V_{IL}$ ) in the [Recommended Operating Conditions](#) table.
  - Inputs are overvoltage tolerant allowing them to go as high as ( $V_I$  max) in the [Recommended Operating Conditions](#) table at any valid  $V_{CC}$ .
2. Recommended Output Conditions
  - Load currents must not exceed ( $I_O$  max) per output and must not exceed (Continuous current through  $V_{CC}$  or GND) total current for the part. These limits are located in the [Recommended Operating Conditions](#) table.
  - Outputs must not be pulled above  $V_{CC}$  under normal operating conditions.

## Typical Application (continued)

### 9.2.3 Application Curve



## 10 Power Supply Recommendations

The power supply can be any voltage between the minimum and maximum supply voltage rating located in the [Recommended Operating Conditions](#) table.

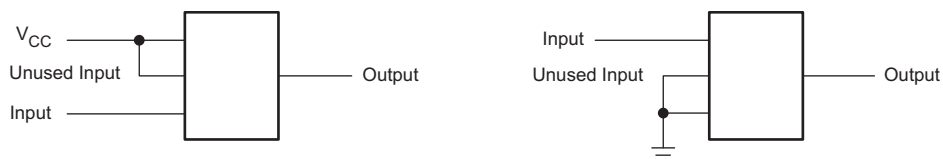
Each V<sub>CC</sub> pin must have a good bypass capacitor to prevent power disturbance. For devices with a single supply, a 0.1-μF capacitor is recommended and if there are multiple V<sub>CC</sub> pins then a 0.01-μF or 0.022-μF capacitor is recommended for each power pin. It is ok to parallel multiple bypass caps to reject different frequencies of noise. 0.1-μF and 1-μF capacitors are commonly used in parallel. The bypass capacitor must be installed as close to the power pin as possible for best results.

## 11 Layout

### 11.1 Layout Guidelines

When using multiple bit logic devices inputs must not ever float. In many cases, functions or parts of functions of digital logic devices are unused; for example, when only two inputs of a triple-input AND gate are used or only 3 of the 4 buffer gates are used. Such input pins must not be left unconnected because the undefined voltages at the outside connections result in undefined operational states. Specified below are the rules that must be observed under all circumstances. All unused inputs of digital logic devices must be connected to a high or low bias to prevent them from floating. The logic level that must be applied to any particular unused input depends on the function of the device. Generally they will be tied to GND or V<sub>CC</sub> whichever make more sense or is more convenient.

### 11.2 Layout Example



## 12 Device and Documentation Support

### 12.1 Documentation Support

#### 12.1.1 Documentation Support

For related documentation, see the following:

*Implications of Slow or Floating CMOS Inputs*, [SCBA004](#)

### 12.2 Community Resources

The following links connect to TI community resources. Linked contents are provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's [Terms of Use](#).

**TI E2E™ Online Community** *TI's Engineer-to-Engineer (E2E) Community*. Created to foster collaboration among engineers. At [e2e.ti.com](#), you can ask questions, share knowledge, explore ideas and help solve problems with fellow engineers.

**Design Support** *TI's Design Support* Quickly find helpful E2E forums along with design support tools and contact information for technical support.

### 12.3 Trademarks

NanoFree, E2E are trademarks of Texas Instruments.  
All other trademarks are the property of their respective owners.

### 12.4 Electrostatic Discharge Caution



These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

### 12.5 Glossary

[SLYZ022](#) — *TI Glossary*.

This glossary lists and explains terms, acronyms, and definitions.

## 13 Mechanical, Packaging, and Orderable Information

The following pages include mechanical packaging and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser based versions of this data sheet, refer to the left hand navigation.

## PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SN74LVC3G34DCTR	ACTIVE	SM8	DCT	8	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	C34 Z	<a href="#">Samples</a>
SN74LVC3G34DCTRG4	ACTIVE	SM8	DCT	8	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	C34 Z	<a href="#">Samples</a>
SN74LVC3G34DCUR	ACTIVE	VSSOP	DCU	8	3000	Green (RoHS & no Sb/Br)	CU NIPDAU   CU SN	Level-1-260C-UNLIM	-40 to 125	(34 ~ C34Q ~ C34R) (CR ~ CZ)	<a href="#">Samples</a>
SN74LVC3G34DCURG4	ACTIVE	VSSOP	DCU	8	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	C34R	<a href="#">Samples</a>
SN74LVC3G34DCUT	ACTIVE	VSSOP	DCU	8	250	Green (RoHS & no Sb/Br)	CU NIPDAU   CU SN	Level-1-260C-UNLIM	-40 to 125	(C34Q ~ C34R) CR	<a href="#">Samples</a>
SN74LVC3G34DCUTG4	ACTIVE	VSSOP	DCU	8	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	C34R	<a href="#">Samples</a>
SN74LVC3G34YZPR	ACTIVE	DSBGA	YZP	8	3000	Green (RoHS & no Sb/Br)	SNAGCU	Level-1-260C-UNLIM	-40 to 85	(C97 ~ C9N)	<a href="#">Samples</a>

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSELETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

<sup>(5)</sup> Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "-" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

<sup>(6)</sup> Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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**TAPE AND REEL INFORMATION**

**QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LVC3G34DCUR	VSSOP	DCU	8	3000	180.0	9.0	2.05	3.3	1.0	4.0	8.0	Q3
SN74LVC3G34DCURG4	VSSOP	DCU	8	3000	180.0	8.4	2.25	3.35	1.05	4.0	8.0	Q3
SN74LVC3G34DCUTG4	VSSOP	DCU	8	250	180.0	8.4	2.25	3.35	1.05	4.0	8.0	Q3
SN74LVC3G34YZPR	DSBGA	YZP	8	3000	178.0	9.2	1.02	2.02	0.63	4.0	8.0	Q1

**TAPE AND REEL BOX DIMENSIONS**

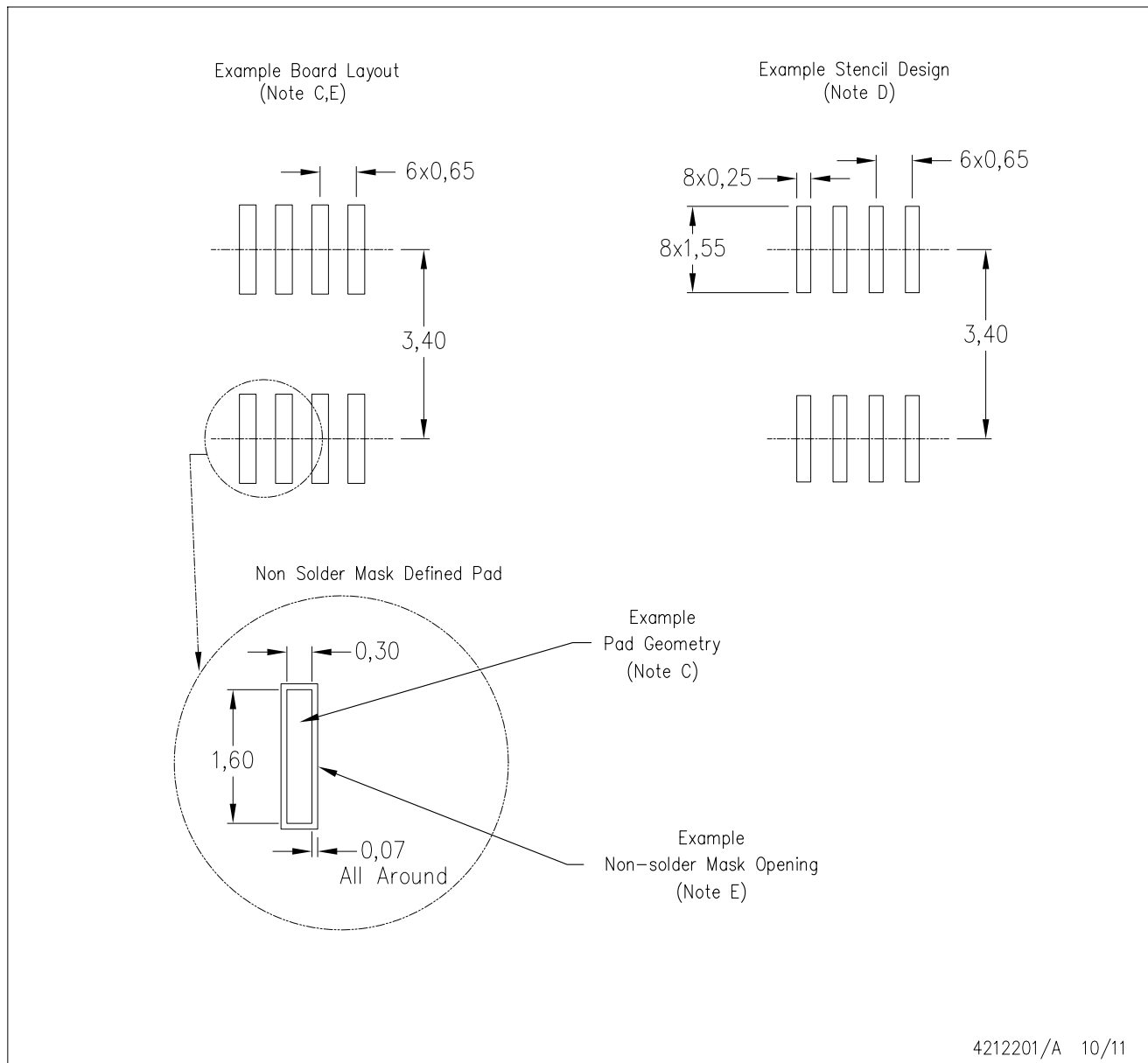

\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LVC3G34DCUR	VSSOP	DCU	8	3000	182.0	182.0	20.0
SN74LVC3G34DCURG4	VSSOP	DCU	8	3000	202.0	201.0	28.0
SN74LVC3G34DCUTG4	VSSOP	DCU	8	250	202.0	201.0	28.0
SN74LVC3G34YZPR	DSBGA	YZP	8	3000	220.0	220.0	35.0



DCT (R-PDSO-G8)

PLASTIC SMALL OUTLINE

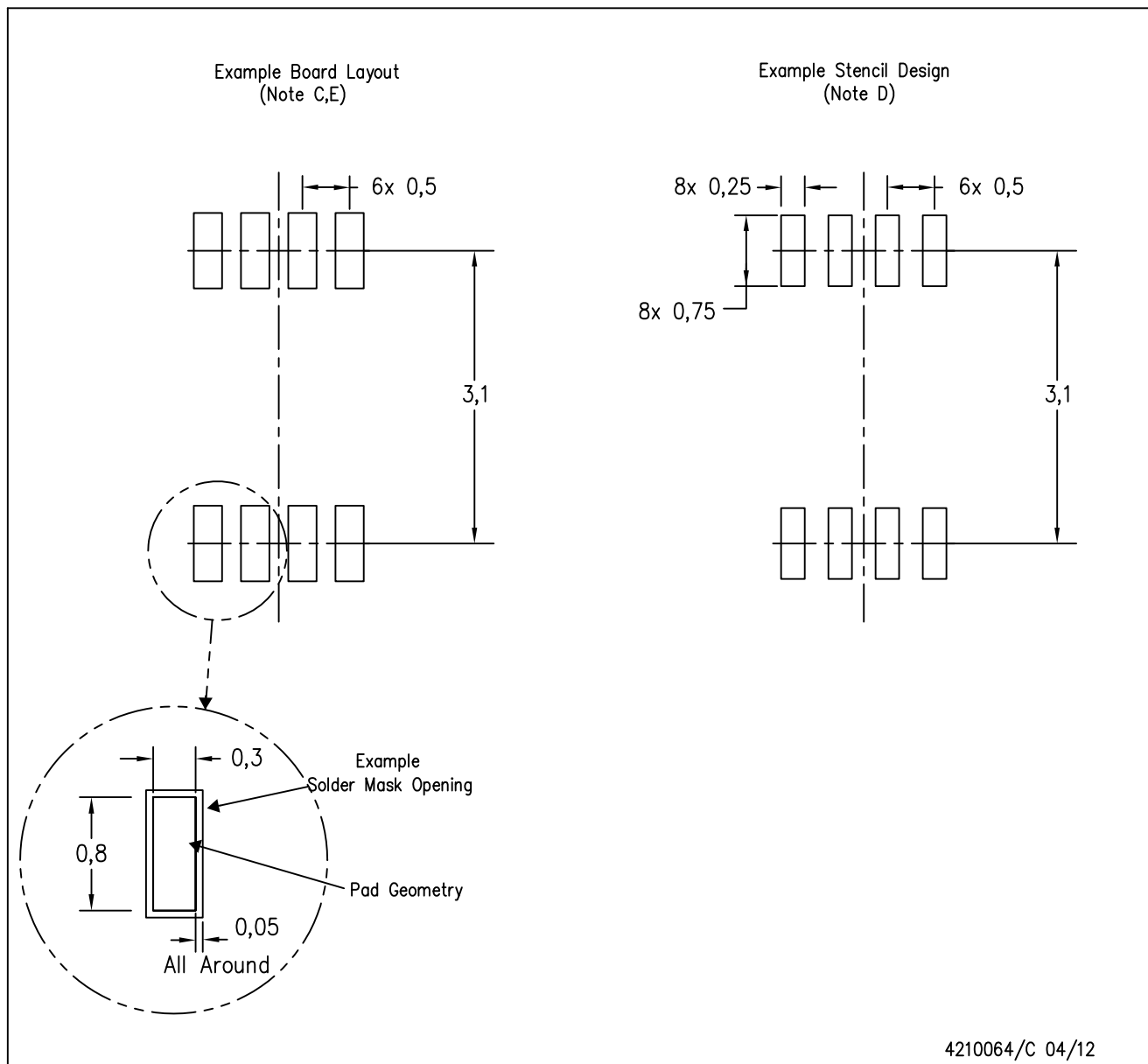


- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Publication IPC-7351 is recommended for alternate designs.
  - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525.
  - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



DCU (S-PDSO-G8)

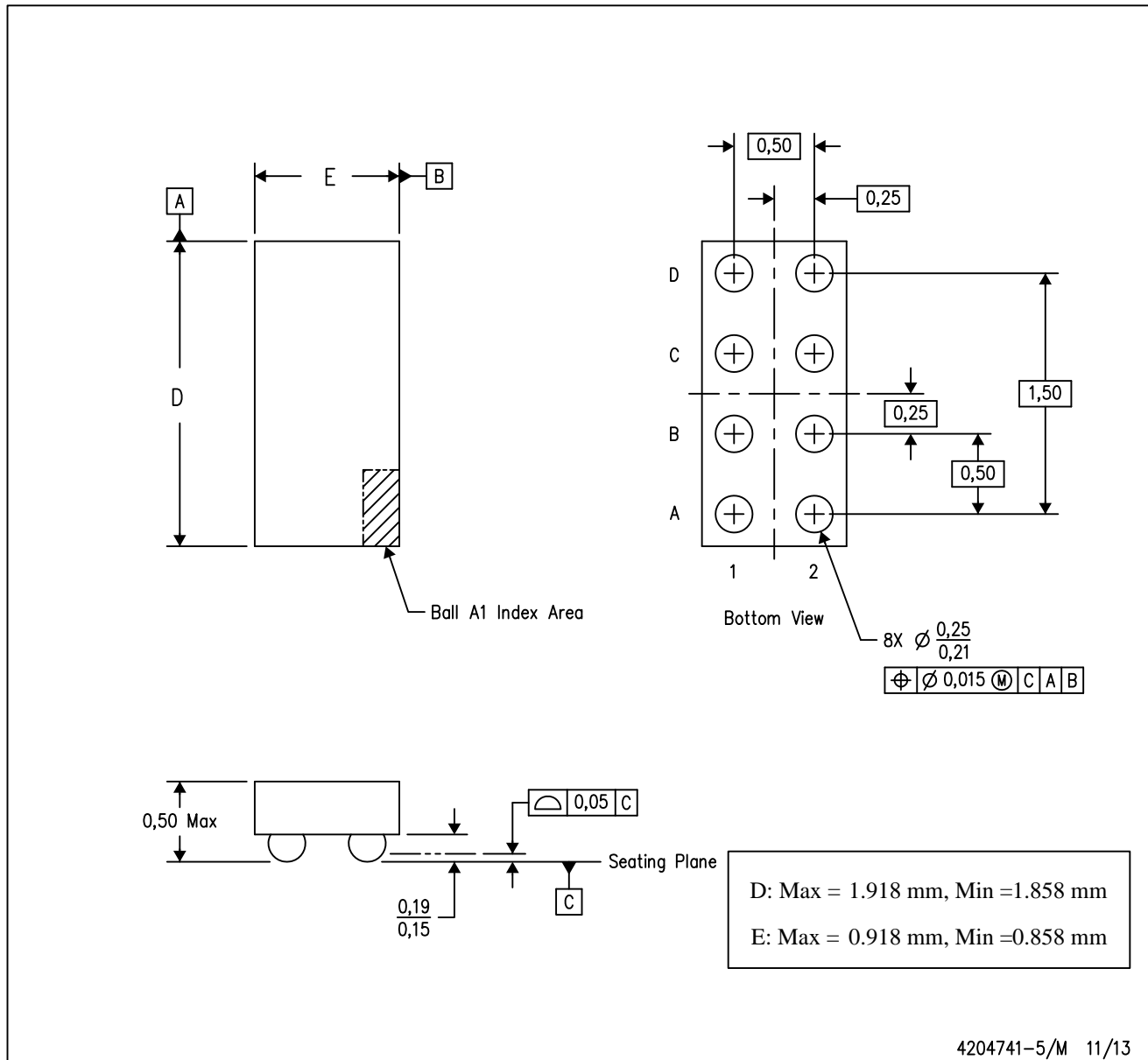
PLASTIC SMALL OUTLINE PACKAGE (DIE DOWN)



- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Publication IPC-7351 is recommended for alternate designs.
  - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
  - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

YZP (R-XBGA-N8)

DIE-SIZE BALL GRID ARRAY



- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
  - B. This drawing is subject to change without notice.
  - C. NanoFree™ package configuration.

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